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(54) **METHODS RELATED TO PREPARATION OF A STENCIL TO RECEIVE A PLURALITY OF IC UNITS**

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See application file for complete search history.

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(57) **ABSTRACT**

A method for preparing a stencil to receive a plurality of IC units, the method comprising the steps of: providing a metal substrate having an array of apertures; applying an adhesive surface to said substrate; removing portions of said adhesive surface corresponding to the apertures in the metal substrate.

6 Claims, 11 Drawing Sheets